

REMARKS

Claims 1-13 remain in the application for consideration of the Examiner with Claims 14-20 standing withdrawn from consideration.

Reconsideration and withdrawal of the outstanding rejections and objections are respectfully requested in light of the above amendments and following remarks.

The Examiner objected to Claims 14-20 because of informalities.

More particularly, the Examiner objected to the status identifier of "original" for Claims 14-20 which in fact Claims 14-20 should have a status identifier of "withdrawn".

By the instant amendment, Claims 14-20 has a status identifier of "withdrawn".

It is respectfully submitted that Claims 14-20 are free from informalities.

Turning now to the art rejections, Claims 1-3, 6-9, 12, and 13 were rejected under 35 U.S.C. § 102(b) as anticipated by Maggio; Claims 1-3, 6-9, 12, and 13 were rejected under 35 U.S.C. § 102(e) as being anticipated by Schroen; Claims 4 and 10 were rejected under 35 U.S.C. § 103 as being unpatentable over Maggio or Schroen in view of Hembree or Hashish; Claims 3 and 9 were rejected under 35 U.S.C. § 103 as being unpatentable over Maggio or Schroen in view of Hembree; and Claims 7 and 13 were rejected under 35 U.S.C. § 103 as being unpatentable over Maggio or Schroen and over alleged applicants admitted prior art (AAPA).

It is respectfully submitted that Maggio does not disclose or suggest the presently claimed invention including the step of cutting through the integrated circuit package to be singulated with a water jet to access an interior portion of the integrated circuit package in independent Claim 1, albeit defined as pressurizing the water jets such that the water jet is operable to cut through the integrated circuit package to

access an interior portion of the integrated circuit package to be singulated in independent Claim 8.

The Examiner's attention is directed to the Abstract of Maggio where Maggio relates to a low particulating circuit board for a disc drive flex assembly.

This has nothing to do with an integrated circuit package.

Schroen does not disclose or suggest the presently claimed invention including cutting through the integrated circuit package to be singulated with a water jet to access an interior portion of the integrated circuit package in the various forms in independent Claims 1 and 8.

Schroen discloses at the paragraph bridging columns 8 and 9 that Figure 3 indicates that the semiconductor wafer 303 while positioned on plastic film support 304, has been separated into a plurality of individual IC chips 306. Typically, this separation is performed by precision sawing; other methods include cutting by laser or water jet. In Figure 3, the sawing streets 307 indicate the grid of separating cuts.

Schroen relates to sawing streets and separating the semiconductor wafer and does not relate to cutting through the integrated circuit package.

Hembree does not disclose or suggest the presently claimed invention including cutting through the integrated circuit package to be singulated with a water jet to access an interior portion of the integrated circuit package in the various forms in independent Claims 1 and 8.

Hembree discloses in column 4, lines 45-65 that break lines can be formed by cracker holes, scoring, water jet abrasion, laser or thermal shock and sawing.

It is respectfully submitted that these break lines are similar to the streets of Schroen and consequently for the same reasons do not disclose or suggest the presently claimed invention.

Hashish does not disclose or suggest the presently claimed invention including cutting through the integrated circuit package to be singulated with a water jet to access an interior portion of the integrated circuit package in independent Claims 1 and 8.

Hashish does not relate to cutting integrated circuit packages.

Romanini does not disclose or suggest the presently claimed invention including cutting through the integrated circuit package to be singulated with a water jet to access an interior portion of the integrated circuit package in independent Claims 1 and 8.

Similar to Hembree, Romanini does not bear any relationship to cutting through the integrated circuit package.

AAPA does not cure the above mentioned defects.

In light of the above, it is respectfully submitted that the present application is in condition for allowance, and notice to that effect is respectfully requested.

While it is believed that the instant response places the application in condition for allowance, should the Examiner have any further comments or suggestions, it is respectfully requested that the Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

To the extent necessary, Applicant petitions for an Extension of Time under 37 CFR 1.136. Please charge any fees in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



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